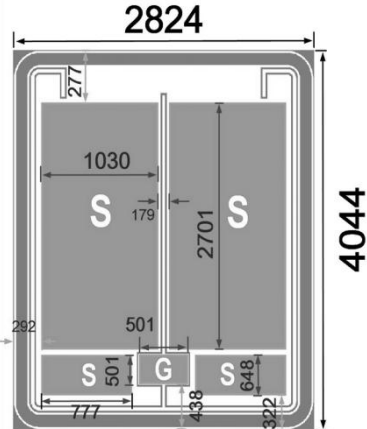
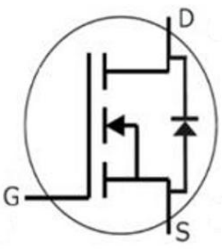


Physical Characteristics

	Die size: 2824 μm x 4044 μm (without scribe line) Gate pad: 501 μm x 501 μm Gross die / per 6" wafer = 1270 pcs	
	Main characteristics: $V_{DS} = 650\text{V}$ $I_D(T_C=25^\circ\text{C}) = 99\text{A}$ $R_{DS(on)MAX} = 38\text{m}\Omega@18\text{V}$	

Mechanical Data

Parameter	Parameter
Nominal Back Metal Composition, Thickness	Ti- Ni - Ag
Nominal Front Metal Composition, Thickness	Al(4 μm)
Wafer Diameter	150mm
Wafer Thickness	175 $\mu\text{m} \pm 10\mu\text{m}$
Scribe line width	80 μm

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Condition	Value	Unit
Drain-Source Voltage	V_{DS}	$V_{GS} = 0\text{V}, I_D = 100\mu\text{A}$	650	V
Gate-Source Voltage	V_{GSmax}	AC ($f > 1\text{Hz}$)	-10/+25	V
Gate-Source Voltage	V_{GSOP}	Static	-4/+18	V
Continuous Drain Current	I_D	$V_{GS} = 18\text{V}, T_C=25^\circ\text{C}$	99	A
	I_D	$V_{GS} = 18\text{V}, T_C=100^\circ\text{C}$	70	
Pulsed Drain Current	$I_{D,pulse}$	Pulse with t_p limited by T_{jmax} at 1ms Pulse with t_p limited by T_{jmax} at 100 μs	157 279	A
Junction Temperature	T_J		-55~ +175	$^\circ\text{C}$
Storage Temperature	T_{STG}		-55~ +175	$^\circ\text{C}$

Note 1: Assumes a $R_{th(jc)}$ will be less than 0.45 K/W.

Electrical characteristics (T_j=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 100μA	650			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 650V, V _{GS} = 0V		1	50	μA
Gate-Source leakage current	I _{GSS}	V _{GS} = 18V, V _{DS} = 0V			250	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 16mA		3.0		V
		V _{DS} = V _{GS} , I _D = 16mA, T _j = 175°C		2.0		
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 18V, I _D = 40A		26	38	mΩ
		V _{GS} = 18V, I _D = 40A, T _j = 175°C		35		
Transconductance	g _{fs}	V _{DS} = 18V, I _D = 40A		27		S
		V _{DS} = 18V, I _D = 40A, T _j = 175°C		25		
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} = 600V, V _{GS} = 0V, f = 1MHz V _{AC} = 25mV		2543		pF
Output Capacitance	C _{oss}			173		
Reverse Transfer Capacitance	C _{rss}			8		
Total Gate Charge	Q _g	V _{DS} = 400V, I _D = 40A V _{GS} = -4V/18V		74.5		nC
Gate-Source Charge	Q _{gs}			29		
Gate-Drain Charge	Q _{gd}			35		
Internal Gate Resistance	R _{G(int)}	f = 1 MHz, V _{AC} = 25mV		1.2		Ω
Source-Drain Diode characteristics						
Diode Forward Current	I _S	V _{GS} = -4V, T _C = 25°C		66		A
Diode Forward voltage	V _{SD}	V _{GS} = -4V, I _{SD} = 20A		4.3		V
		V _{GS} = -4V, I _{SD} = 20A, T _j = 175°C		3.7		V
Diode Pulse Current	I _{S,pulse}	V _{GS} = -4V, pulse width t _p limited by T _{jmax}		157		A